

General Chair

Guillermo Rafael-Valdivia

Universidad Catolica San Pablo

grafaelv@ucsp.edu.pe

General Co-Chair

Patrick Roblin

Ohio State University

roblin.1@osu.edu

Technical Program Committee Chair

Efrain Zenteno-Bolaños

Universidad Catolica San Pablo

ezenteno@ucsp.edu.pe

Technical Program Committee Co-Chair

Emmanouil Tentzeris

Georgia Tech, Atlanta

etentze@ece.gatech.edu

Publications Chair

Gonzalo Fernandez Del Carpio

gfernandezdc@ucsp.edu.pe

Financial Chair (treasurer)

Efrain Mayhua-Lopez

Universidad Catolica San Pablo

emayhua@ucsp.edu.pe

Exhibits Chair

Agustin Vijande

Keysight

agustinvijande@aqt.com.ar

CALL FOR PAPERS

The Technical Program Committee of the 2016 IEEE MTT-S Latin America Microwave Conference (LAMC) wishes to invite original contributions to this event. The conference includes, but is not limited to, the following topics:

1. Passive components, circuits and devices (planar and nonplanar components and circuits, filters and multiplexers, tunable devices, and metamaterials).
2. Active devices, circuits and subsystems (RFICs & MMIC design, power amplifiers, linearization techniques, low-noise circuits, signal generation, conversion & control modules, linear and non-linear modeling and characterization).
3. RF systems and applications (microwave systems and front-ends industrial scientific and medical applications, navigation systems, intelligent transportation systems, imaging, sensors, wireless power transmission).
4. Communication systems (terrestrial, vehicular, satellite and indoor applications, wireless and cellular communication systems).
5. Active antennas (phase arrays, integrated antennas, smart antennas, digital-beam forming and MIMO).
6. Signal-power integrity and high-speed digital techniques (EM interference and compatibility, high-speed interconnects, post-silicon validation techniques, power delivery networks, computer simulations and measurements).
7. CAD techniques for RF and microwave engineering (surrogate-based modeling and optimization, space mapping-based methods, model order reduction techniques, statistical analysis and design, EM-based and multiphysics design optimization, EM field theory, time and frequency-domain numerical techniques).

DEADLINES

August, 06, 2018 Electronic Abstract / Summary due in PDF format

November 08, 2018 Publication - ready paper due in PDF format

Papers submitted to LAMC 2018 will be peer reviewed and evaluated based on originality, quantitative contents, clarity, and interest to the audience. The review process will be single-blind. LAMC will use IEEE EDAS as the electronic paper management system. All accepted and presented papers will be published in the LAMC Conference Proceedings and submitted for inclusion in the IEEE Xplore Digital Library.

English will be the official language of the conference. Prospective authors are cordially invited to submit a three - page two-column manuscript, following the instructions available at the conference website (<http://lamc-ieee.org>).

EXHIBIT & SPONSORSHIP

The IEEE MTT-S Latin America Microwave Conference also offers an outstanding exhibition and sponsorship opportunity. Please contact our Exhibits Chair.

